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URL for Additional Information

PART INFORMATIONMfg Item NumberSVF331R3K2CKU2Mfg Item NameLQFP-EP 176 24*24*1.6

SUPPLIER

Company Name

Company Unique ID

Response Date

Freescale Semiconductor Inc
14-141-7928
2016-08-11

Response Document ID 00C2A1.0 Freescale Semiconductor Inc Contact Name Contact Title Product Technical Support **Contact Phone** 1-800-521-6274 Contact Email support@freescale.com **Authorized Representative** Daniel Binyon Representative Title **EPP Customer Response** Representative Phone 512-895-3406 Representative Email eppanlst@freescale.com

DECLARATION

EU RoHS Yes
Pb Free Yes
HalogenFree Yes

Plating Indicator
EU RoHS Exemption(s)

MANUFACTURING

Mfg Item Number

SVF331R3K2CKU2

LOEP-EP 176 24*24*1

LQFP-EP 176 24*24*1.6 Mfg Item Name Version ALL 1.866700 Weight UoM Unit Volume EACH J-STD-020 MSL Rating 3 Peak Processing Temperature 260 C Max Time at Peak Temperature 40 seconds Number of Processing Cycles

e3

www.freescale.com



RoHS								
RoHS Directive	2011/65/EU							
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium							
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Su							
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above							
Supplier Acceptance	Accepted							
Signature	Daniel Binyon							
Exemption List Version	2012/51/EU							
List of Freescale Accepted Exemptions	6(a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight							
	6(b): Lead as an alloying element in aluminium containing up to 0.4% lead by weight							
	6(c): Copper alloy containing up to 4% lead by weight							
	7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)							
	7(b): Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications							
	7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound							
	7(c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher							
	7(c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC							
	7(c)-IV: Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors							
	15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages							



Homogeneous Material	Weight				SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Lead Frame Plating	0.0039					g				
_ead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1	0.00000078	g	200	0.02	0	0
Lead Frame Plating		Metals	Tin, metal	7440-31-5	0.00389922	g	999800	99.98	2088	0.2088
Epoxy Die Attach	0.0024					g				
Epoxy Die Attach		Solvents, additives, and other materials	Proprietary Material-Other acrylates	-	0.0003	g	125000	12.5	160	0.016
Epoxy Die Attach		Plastics/polymers	Proprietary Material-Other Epoxy resins	-	0.00006	g	25000	2.5	32	0.0032
poxy Die Attach		Solvents, additives, and other materials	Other organic Silicon Compounds	-	0.00003	g	12500	1.25	16	0.0016
Epoxy Die Attach		Metals	Silver, metal	7440-22-4	0.001872	g	780000	78	1002	0.1002
Epoxy Die Attach		Plastics/polymers	Proprietary Material-acrylonitrile/butadiene copolymer, carboxyl terminated	-	0.000138	g	57500	5.75	73	0.0073
Bonding Wire, Copper	0.003					g				
Bonding Wire, Copper		Metals	Copper, metal	7440-50-8	0.00291	g	970000	97	1558	0.1558
Bonding Wire, Copper		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-	0.00009	g	30000	3	48	0.0048
Copper Lead Frame	0.7268					g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8	0.68360046	g	940562	94.0562	366207	36.6207
Copper Lead Frame		Solvents, additives, and other materials	Silicon	7440-21-3	0.0052693	g	7250	0.725	2822	0.2822
Copper Lead Frame		Metals	Iron, metal	7439-89-6	0.0009085	g	1250	0.125	486	0.0486
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1	0.00022749	g	313	0.0313	121	0.0121
Copper Lead Frame		Metals	Magnesium, metal	7439-95-4	0.0012719	g	1750	0.175	681	0.0681
Copper Lead Frame		Metals	Manganese, metal	7439-96-5	0.00045425	g	625	0.0625	243	0.0243
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0	0.0232576	g	32000	3.2	12459	1.2459
Copper Lead Frame		Metals	Silver, metal	7440-22-4	0.007268	g	10000	1	3893	0.3893
Copper Lead Frame		Metals	Zinc, metal	7440-66-6	0.0045425	g	6250	0.625	2433	0.2433
Die Encapsulant, Halogen-free	1.1114					g				
Die Encapsulant, Halogen-free		Plastics/polymers	Epoxy resin, EPON Resin 8091	25928-94-3	0.05557	g	50000	5	29769	2.9769
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4	0.005557	g	5000	0.5	2976	0.2976
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Silicone modified epoxy resin	218163-11-2	0.05557	g	50000	5	29769	2.9769
Die Encapsulant, Halogen-free		Plastics/polymers	Phenolic Resin	125133-38-2	0.05557	g	50000	5	29769	2.9769
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9	0.105583	g	95000	9.5	56561	5.6561
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0	0.83355	g	750000	75	446550	44.655
Silicon Semiconductor Die	0.0192					g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-	0.000384	g	20000	2	205	0.0205
Silicon Semiconductor Die		Glass	Silicon, doped		0.018816	q	980000	98	10079	1.0079



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